ASSOCIATION CONNECTING ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® international and Pa	PC. Bannockl	burn, Illinois, A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declaration entries the declaration entries and t	on of the su	bstances v s all lower	vithin the manufactu level materials for w	rer listed in the rest of the	tem. Note: nanufacture	if the item is an as er has engineering	sembly with low responsibility.	
				Form Type Distribute					ials and Mfg Information					
upplier Information														
mpany name* Company un			inique ID			Unique ID Authority				Respon	Response Date*			
On Semiconductor										2020-05	2020-05-26			
ntact Name Title - Contact			act			Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards Product Envi			viro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative			esentative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product I			oduct Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version	Version Manufacturing Site			Weight*	UOM	Unit Type	
	FOD312	FOD3120SD 8PW 2.5A G		GD T&R		2020-05-26		L	LITEONFG		601.011	mg	Each	
Ianufacturing Proccess Informa	tion							·						
Terminal Plating / Grid Array M	aterial	Ferminal Base A	Alloy J-STD-020 MSL Rat		L Rating	Peak Proce	ak Process Body Temperatu		ure Max Time at Peak Tempera		ture Num	ber of Reflow Cyc	eles	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy	1			260 C		30	seconds 3					
omments														
vel 1 - maximum time at peak temperat	ure during so	dering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	toHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl hthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Coating	6.13	mg	Supplier	Ethylbenzene	100-41-4		0.613	mg
			Supplier	Filler (SiO2)	68909-20-6		2.452	mg
			Supplier	Xylene	1330-20-7		3.065	mg
Die	4.011	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.281	mg
			Supplier	Silicon (Si)	7440-21-3		3.73	mg
Die Attach	0.25	mg	Supplier	Silver (Ag)	7440-22-4		0.1873	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.0627	mg
Lead Frame	113.441	mg	Supplier	Silver (Ag)	7440-22-4		0.7151	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1362	mg
			Supplier	Iron (Fe)	7439-89-6		2.6124	mg
			Supplier	Copper (Cu)	7440-50-8		109.943	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0343	mg
Mold Compound-White	459.747	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		114.9368	mg
			В	Brominated Bisphenol A Diglycidyl Ether	40039-93-8		13.7924	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		62.0658	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		13.7924	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		229.8735	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		25.2861	mg
Plating	1.559	mg	Supplier	Tin (Sn)	7440-31-5		1.559	mg
Wire Bond - Au	15.873	mg	Supplier	Gold (Au)	7440-57-5		15.873	mg